



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-C167CS-L33M CA+		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000970688						
<b>Package</b>		PG-MQFP-144-8		<b>Weight*</b>		4198.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	36.251	0.86	0.86	8634	8634
leadframe	non noble metal	magnesium	7439-95-4	0.976	0.02		232	
	inorganic material	silicon	7440-21-3	4.227	0.10		1007	
	non noble metal	nickel	7440-02-0	19.510	0.46		4647	
	non noble metal	copper	7440-50-8	625.625	14.90	15.48	149013	154899
wire	noble metal	gold	7440-57-5	5.612	0.13	0.13	1337	1337
encapsulation	organic material	carbon black	1333-86-4	10.410	0.25		2480	
	plastics	epoxy resin	-	440.706	10.50		104968	
	inorganic material	silicondioxide	60676-86-0	3019.012	71.93	82.68	719075	826523
leadfinish	non noble metal	tin	7440-31-5	19.066	0.45	0.45	4541	4541
plating	noble metal	silver	7440-22-4	10.582	0.25	0.25	2521	2521
glue	plastics	acrylic resin	-	1.297	0.03		309	
	noble metal	silver	7440-22-4	5.190	0.12	0.15	1236	1545
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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